Multilayer Ceramic Chip Capacitors

C1005X8R1E103K050BA



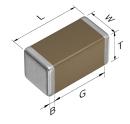






TDK item description C1005X8R1E103KT****

Applications	Commercial Grade	
	Please refer to Part No. <u>CGA2B2X8R1E103K050BA</u> for Automotive use.	
Feature	150°C High Temperature Application	
Series	C1005 [EIA 0402]	
Status	Production	



	Size	
Length(L)	1.00mm ±0.05mm	
Width(W)	0.50mm ±0.05mm	
Thickness(T)	0.50mm ±0.05mm	
Terminal Width(B)	0.10mm Min.	
Terminal Spacing(G)	0.30mm Min.	
Recommended Land Pattern (PA)	0.30mm to 0.50mm	
Recommended Land Pattern (PB)	0.35mm to 0.45mm	
Recommended Land Pattern (PC)	0.40mm to 0.60mm	

	Electrical Characteristics	
Capacitance	10nF ±10%	
Rated Voltage	25VDC	
Temperature Characteristic	X8R(±15%)	
Dissipation Factor (Max.)	3%	
Insulation Resistance (Min.)	10000ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	10000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

C1005X8R1E103K050BA

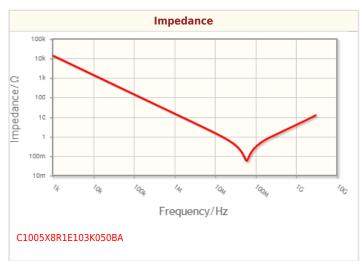


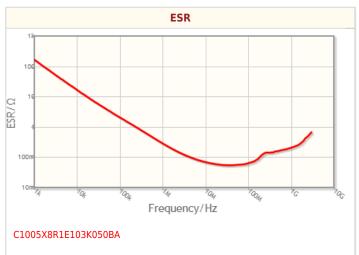


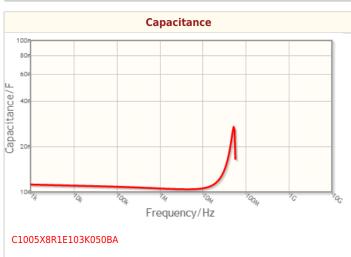


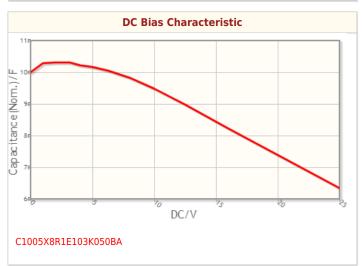


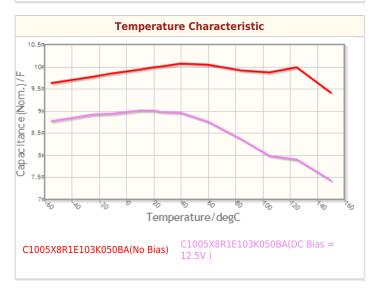
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

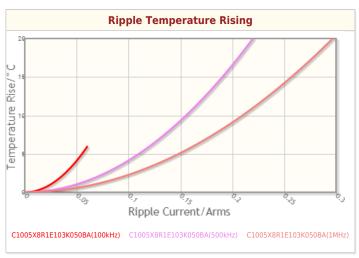












[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

C1005X8R1E103K050BA

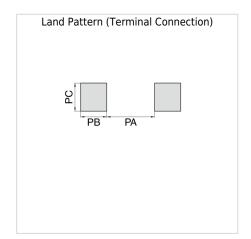








Associated Images



[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.